

SOT846-1

plastic thermal enhanced ball grid array package; 760 balls;
body 40 x 40 x 1.75 mm; heatsink

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|---|
| Terminal position code | B (bottom) |
| Package type descriptive code | HBGA760 |
| Package type industry code | HBGA760 |
| Package style descriptive code | HBGA (thermal enhanced ball grid array) |
| Package style suffix code | NA (not applicable) |
| Package body material type | P (plastic) |
| JEDEC package outline code | MS-034 |
| Mounting method type | S (surface mount) |
| Issue date | 19-8-2005 |

Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-------|-----|------|------|------|
| D | package length | 39.8 | - | 40 | 40.2 | mm |
| E | package width | 39.8 | - | 40 | 40.2 | mm |
| A | seated height | [tbd] | - | 2.55 | 2.55 | mm |
| A ₂ | package height | 1.6 | - | 1.75 | 1.85 | mm |
| n ₂ | actual quantity of termination | - | - | 760 | - | |



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2. Package outline

HBGA760: plastic thermal enhanced ball grid array package; 760 balls;
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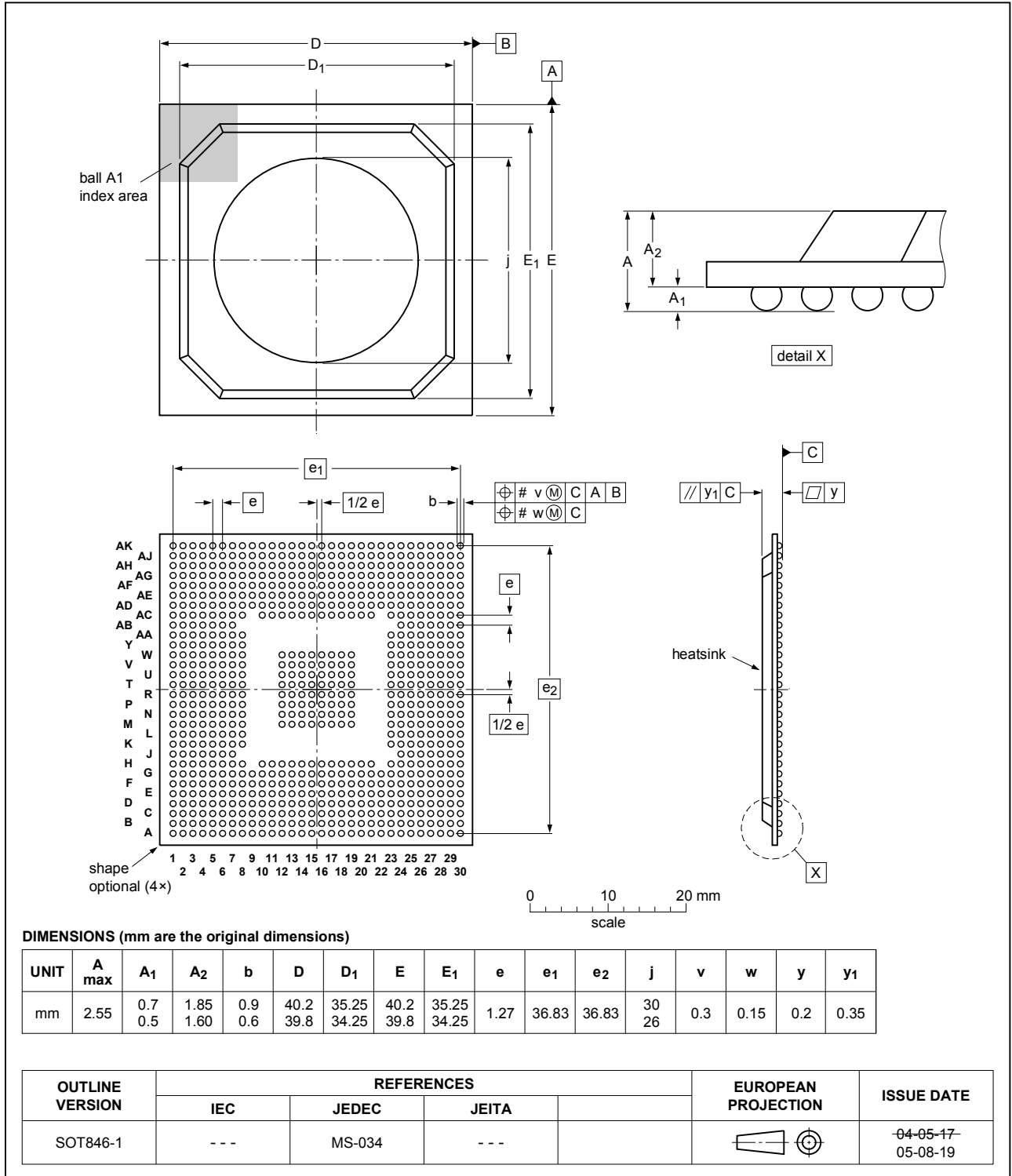


Fig. 1. Package outline HBGA760 (SOT846-1)

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3. Soldering

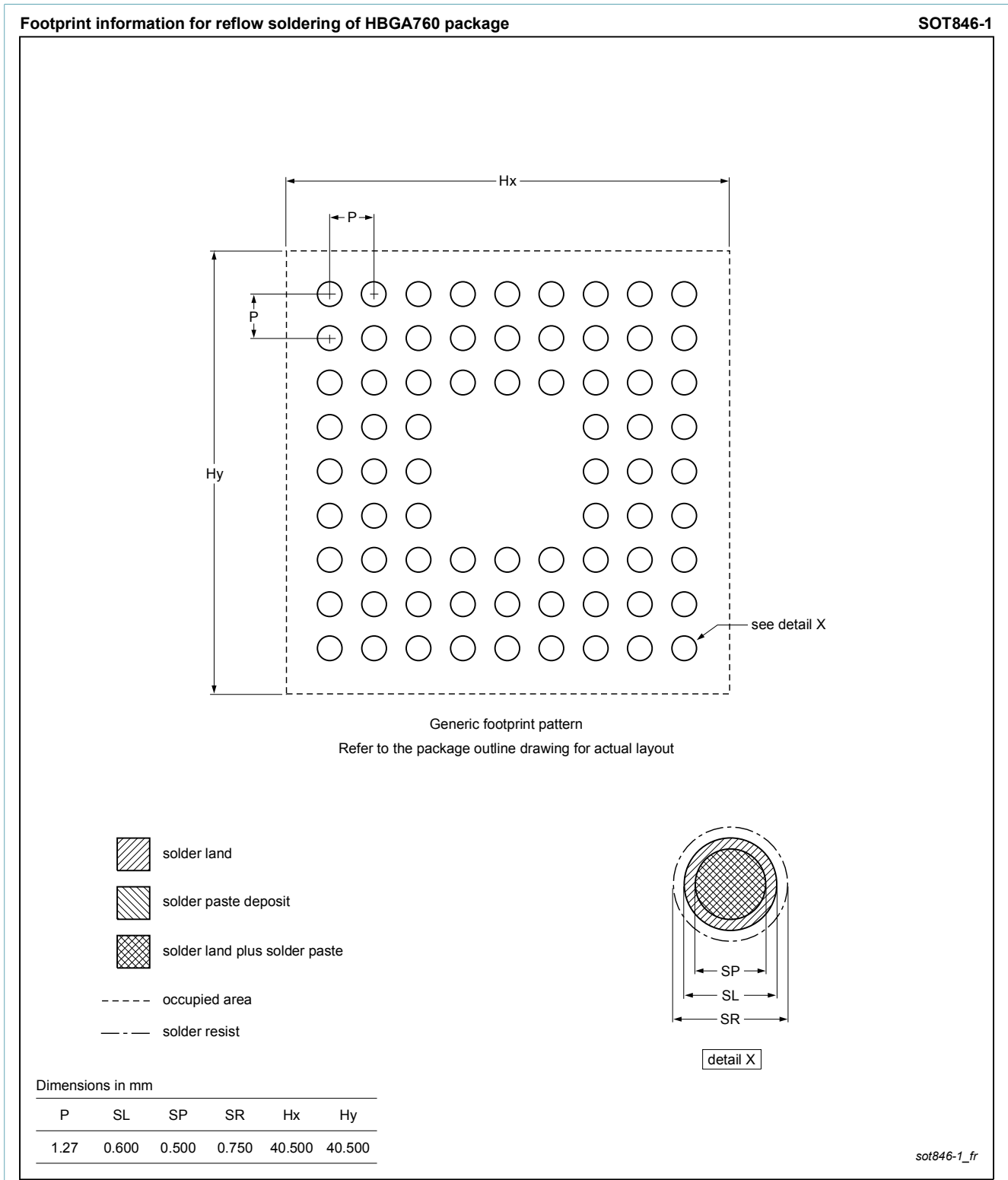


Fig. 2. Reflow soldering footprint for HBGA760 (SOT846-1)

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4. Legal information

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Date of release: 8 February 2016
